





Electrical Specifications:

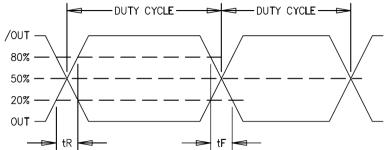
Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Frequency of Operation	Fo		156.253906		MHz	
		Free	quency Stabi	lity		
Frequency Stability	∆F/F	-25	-25 +25 ppm voltage, shock, v year agi		Inclusive of initial tolerance, deviation over temperature, supply voltage, reflow soldering, shock, vibration, and 5 year aging at +40 °C mean temperature.	
			RF Output			
Output Type		LV	PECL Compatik	ole		
Output Load		50	Ω to (Vcc-2.0) \	/DC	V	
Symmetry (duty cycle)	Vон	45		55	%	Ref. to 50% of waveform
Logic Level "1"	V _{OH}	V _{cc} -1.025			V	
Logic Level "0"	T _{DC}			V _{cc} -1.620	V	
Rise/Fall Time	Tr/Tf			0.6	nS 20% to 80% of waveform	
Start-up Time	Tsu			10	mS	$T_{ambient} = +25^{\circ}C$
Enable Logic		70% V _{CC} or N/C			V	Pad 1: Output Enabled
Disable Logic				30% Vcc	V	Pad 1: Output Disabled to high-Z
	S	upply Volta	ge & Power C	onsumption	n	
Operating Voltage	Vcc	3.135	3.3	3.465	V	
Supply Current	Icc			90	mA	
		Ot	her Parameter	_		
Phase Jitter (RMS)	ΦJ			1.0	pS	12 KHz to 20 MHz







Output Waveform:



Environmental & Packaging Requirements:

Operating Temperature	TA	-40		+85	°C				
Storage Temperature	Ts	-55		+125	°C				
Mechanical Shock	Per MIL-S	TD-202, M	ethod 213, Co	ondition C (1	00 g's, 6 ms (duration, ½ sinewave)			
Vibration	Per MIL-S	TD-202, M	ethod 201 & 2	204 (10 g's fi	rom 10-2000	Hz)			
Thermal Cycle	Per MIL-S	Per MIL-STD-883, Method 1010, B (-55°C to 125°C, 15 min. dwell, 10 cycles)							
Hermeticity	Per MIL-STD-202, Method 112 (1 x 10 ⁻⁸ atm cc/s of Helium)								
Moisture Sensitivity Level (MSL)	MSL 1								
Solderability	Per EIAJ-STD-002								
Max. Soldering Conditions	See solder profile, Figure 1								
Package Type	6-pad 5.0	X 7.0 X 1.9) mm leadless	ceramic. Ro	oHS compliar	nt.			

Marking, Pin Out:

Pad	Function
1	Enable/Disable
2	N/C
3	Ground
4	Output
5	Complementary Output
6	+V _{cc}

Part Marking				
Line 1	M2702S001			
Line 2	156M2539			
Line 3	M yywwvv			

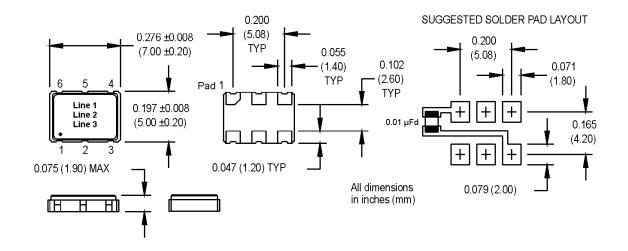
	Legend				
уу	yy Year				
ww	Work Week				
vv	Factory Code				



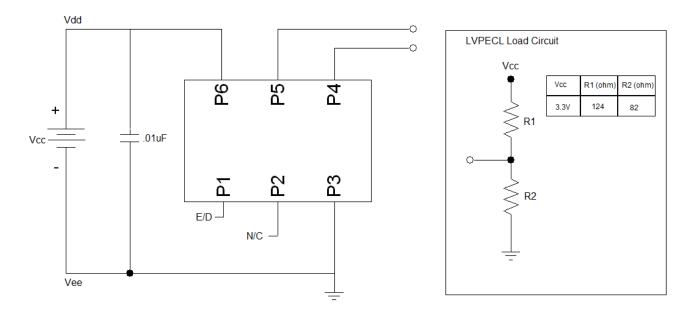




Dimensions:



Typical Test Circuit & Load Circuit Diagrams:



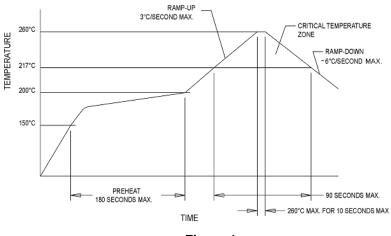
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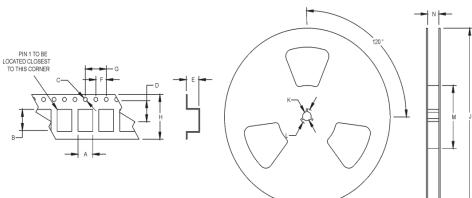
Soldering Conditions:





Tape and Reel Specifications:

All units in mm



Tape and Reel Specifications											
А	В	С	D	E	F	G	Н	J	K	L	Μ
5.32	7.28	1.5	7.5	2.2	4	8	16	178	13.5	24.8	80

Datasheet Revision Table:

Date	Rev.	Author	Details of Revision
01/12/16	0	DCO	Original release